

What is claimed is:

1. A device comprising an electrical circuit carried by a carrier element, an electrically  
conductive structure being provided on a surface of the carrier element, wherein one  
5 or more further components of the electrical circuit are arranged on the side of the  
electrically conductive structure facing the carrier element.
2. A device according to claim 1, wherein the carrier element consists of plastics  
material.
- 10 3. A device according to claim 1, wherein the components of the electrical circuit  
arranged on the side of the electrically conductive structure facing the carrier element  
are fully or partly embedded in the carrier element .
- 15 4. A device according to claim 1, wherein the electrically conductive structure comprises  
a single-layer or multi-layer thin-film structure .
5. A device according to claim 1, wherein the electrically conductive structure comprises  
a single-layer or multi-layer thick-film structure.
- 20 6. A device according to claim 1, wherein the electrically conductive structure comprises  
one or more single-layer or multi-layer electrically conductive films.
7. A device according to claim 1, wherein the electrically conductive structure is  
25 arranged and constructed so that it forms passive and/or active electronic  
components.
8. A device according to claim 1, wherein the electrically conductive structure is  
arranged and constructed so that it forms strip conductors connecting specific points  
30 on the surface of the carrier element with one another.

9. A device according to claim 1, wherein components of the electrical circuit are also arranged on the side of the electrically conductive structure remote from the carrier element, said components preferably being adhesively secured or soldered on said structure.

10. A device according to claim 1, wherein the components of the electrical circuit arranged on the side of the electrically conductive structure facing the carrier element comprise active or passive components, preferably one or more semi-conductor chips.

11. A device according to claim 1, wherein the components of the electrical circuit arranged on the side of the electrically conductive structure facing the carrier element comprise one or more connecting devices for electrical connection of the arrangement to other components of the system containing the arrangement, said connecting devices preferably comprising one or more electrical connectors.

12. A device according to claim 11, wherein the connecting devices comprise one or more contact elements suitable for soldering the arrangement onto an electrical printed circuit board.

13. A device according to claim 1, wherein the components of the electrical circuit arranged on the side of the electrically conductive structure facing the carrier element are elements designed for surface mounting, said elements preferably being elements soldered onto or adhesively secured to the side of the electrically conductive structure facing the carrier element.

14. A method for manufacture of a device having an electrical circuit carried by a carrier element and having an electrically conductive structure provided on a surface of the carrier element, comprising the steps of:

- a) applying the electrically conductive structure to a temporary substrate ,
- b) mounting further components of the electrical circuit on the electrically conductive structure,

- c) applying a composition forming the carrier element to the side of the temporary substrate carrying the said circuit parts, and
- d) removing the temporary substrate.

- 5 15. A method according to claim 14, wherein applying the electrically conductive structure to the temporary substrate comprises applying of a single-layer or multi-layer thin-film structure to the temporary substrate.
- 10 16. A method according to claim 14, wherein applying the electrically conductive structure to the temporary substrate comprises applying of a single-layer or multi-layer thick-film structure to the temporary substrate.
- 15 17. A method according to claim 14, wherein applying the electrically conductive structure to the temporary substrate comprises applying of one or more single-layer or multi-layer electrically conductive films to the temporary substrate.
- 20 18. A method according to claim 14, wherein applying the electrically conductive structure to the temporary substrate is effected such that the layer structure of the electrically conductive structure is opposite to the layer structure of the electrically conductive structure present in the finished arrangement on the carrier element .
- 25 19. A method according to claim 14, wherein mounting the further components of the electrical circuit on the electrically conductive structure is effected by adhesion or soldering.
- 30 20. A method according to claim 14, wherein applying the composition forming the carrier element is effected by casting or injection-moulding plastics material around the components of the electrical circuit provided on the temporary substrate .
21. A method according to claim 14, wherein removing the temporary substrate is effected by etching away of the same.

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22. A method according to claim 14, wherein after removing the temporary substrate further components of the electrical circuit are mounted on the side of the electrically conductive structure remote from the carrier element.

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